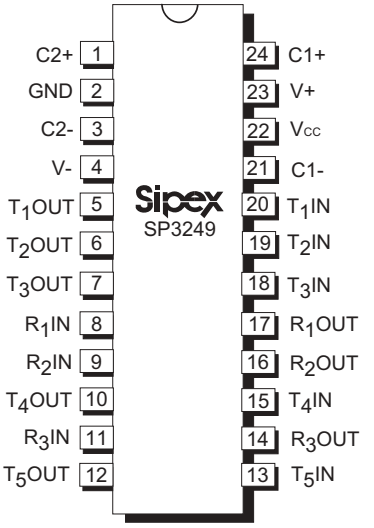
Intelligent +3.0V to +5.5V RS-232 Transceivers

Complete DCE Serial Port

FEATURES

- Meets true EIA/TIA-232-F Standards from a +3.0V to +5.5V power supply
- Interoperable with EIA/TIA-232 and adheres to EIA/TIA-562 down to a +2.7V power source
- Minimum 250Kbps data rate under load
- Regulated Charge Pump Yields Stable RS-232 Outputs Regardless of V_{CC} Variations
- ESD Specifications: ±2kV Human Body Model



DESCRIPTION

The SP3249 device is an RS-232 transceiver solution intended for portable or hand-held applications such as notebook and palmtop computers. The SP3249 uses an internal high-efficiency, charge-pump power supply that requires only 0.1µF capacitors in 3.3V operation. This charge pump and Sipex's driver architecture allow the SP3249 device to deliver compliant RS-232 performance from a single power supply ranging from +3.0V to +5.0V. The SP3249 is a 5-driver/3-receiver device, ideal for laptop/notebook computer and PDA applications.

RELATED DEVICES

Device	Power Supplies	RS-232 Drivers	RS-232 Receivers	External Components	AUTO ON-LINE® Circuitry	TTL 3-State	No. of Pins
SP3249	+3.0V to +5.5V	5	3	4 capacitors	NO	NO	24
SP3223	+3.0V to +5.5V	2	2	4 capacitors	YES	YES	20
SP3243	+3.0V to +5.5V	3	5	4 capacitors	YES	YES	28
SP3238	+3.0V to +5.5V	5	3	4 capacitors	YES	YES	28
SP3239	+3.0V to +5.5V	5	3	4 capacitors	NO	YES	28

Applicable U.S. Patents - 5,306,954; and other patents pending.

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ABSOLUTE MAXIMUM RATINGS

These are stress ratings only and functional operation of the device at these ratings or any other above those indicated in the operation sections of the specifications below is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability and cause permanent damage to the device.

V_{CC} ..... -0.3V to +6.0V
V+ (NOTE 1) ..... -0.3V to +7.0V
V- (NOTE 1) ..... +0.3V to -7.0V
V+ + |V-| (NOTE 1) ..... +13V
I_{CC} (DC V_{CC} or GND current) ..... ±100mA

Input Voltages
TxIN ..... .-0.3V to +6.0V
RxIN ..... ±25V
Output Voltages
TxOUT ..... ±13.2V
RxOUT ..... -0.3V to (V_{CC} + 0.3V)
Short-Circuit Duration
TxOUT ..... Continuous
Storage Temperature ..... -65°C to +150°C

Note 1: V+ and V- can have maximum magnitudes of 7V, but their absolute difference cannot exceed 13V.

ELECTRICAL CHARACTERISTICS

V_{CC} = +3.0 to +5.5, C1 -C4 = 0.1μF (tested at 3.3V ± 5%), C1-C4 = 0.22μF (tested at 3.3V ± 10%), C1 = 0.047μF, and C2-C4 = 0.33μF (tested at 5.0V ± 10%), T_A = T_{MIN} to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.)

PARAMETER	MIN.	TYP.	MAX.	UNITS	CONDITIONS
Supply Current		0.3	1.0	mA	$V_{CC,}$ no load
LOGIC INPUTS AND RECEIVER OUTPUTS					
Input Logic Threshold LOW HIGH	 2.4		0.8	V	V_{CC} = +3.3V or +5.0V, TxIN
Input Leakage Current		±0.01	±1.0	μA	TxIN, T_A = 25° C
Output Voltage LOW			0.4	V	I_{OUT} = 1.6mA
Output Voltage HIGH	V_{CC} - 0.6	V_{CC} - 0.1		V	I_{OUT} = -1.0mA
DRIVER OUTPUTS					
Output Voltage Swing	±5.0	±5.4		V	All driver outputs loaded with 3KΩ to GND
Output Resistance	300			Ω	V_{CC} = V+ = V- = 0V, V_{OUT} = ±2V
Output Short-Circuit Current		±35	±60	mA	V_{OUT} = GND
RECEIVER INPUTS Input Voltage Range	 -25		 25	 V	
Input Threshold LOW	0.6	1.2		V	V_{CC} = 3.3V
Input Threshold LOW	0.8	1.5		V	V_{CC} = 5.0V
Input Threshold HIGH		1.5	2.4	V	V_{CC} = 3.3V
Input Threshold HIGH		1.8	2.4	V	V_{CC} = 5.0V
Input Hysteresis		0.5		V	
Input Resistance	3	5	7	kΩ	

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ELECTRICAL CHARACTERISTICS

V_{CC} = +3.0 to +5.5, C1 -C4 = 0.1µF (tested at 3.3V ± 5%), C1-C4 = 0.22µF (tested at 3.3V ± 10%), C1 = 0.047µF, and C2-C4 = 0.33µF (tested at 5.0V ± 10%), $T_A = T_{MIN}$ to T_{MAX}, unless otherwise noted. Typical values are at T_A = +25°C.)

PARAMETER	MIN.	TYP.	MAX.	UNITS	CONDITIONS
TIMING CHARACTERISTICS					
Maximum Data Rate	250			kbps	R_L = 3kΩ, C_L = 1000pF, one driver switching
Receiver Propagation Delay t_{PHL} t_{PLH}		 0.15 0.15		µS	Receiver input to receiver output, C_L = 150pF
Receiver Output Enable Time		200		ns	Normal operation
Receiver Output Disable Time		200		ns	Normal operation
Driver Skew		100		ns	I t_{PLH} - t_{PHL} I,T_A = 25°C
Receiver Skew		50		ns	I t_{PLH} - t_{PHL} I
Transition-Region Slew Rate			30	V/µs	V_{CC} = 3.3V, R_L = 3kΩ, T_{AMB} = 25°C, measurements taken from -3.0V to +3.0V or +3.0V to -3.0V

TYPICAL PERFOMANCE CHARACTERISTICS

Unless otherwise noted, the following perfomance characteristics apply for V_{CC} = +3.3V, 250kbps data rate, all drivers loaded with 3kΩ, 0.1µF charge pump capacitors, and T_{AMB} = +25°C.

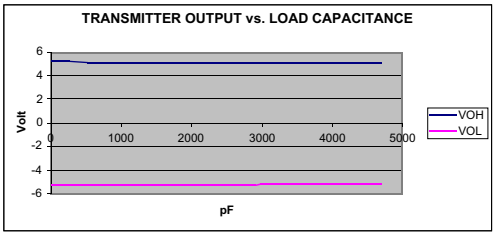

Figure 1. Transmitter Output VS. Load Capacitance when Transmitting Data

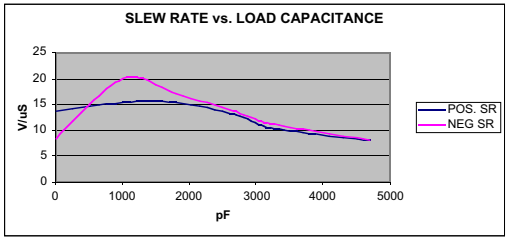

Figure 2. Slew Rate VS. Load Capacitance when Transmitting Data

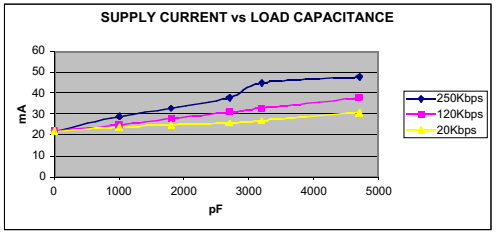

Figure 3. Supply Current VS. Load Capacitance when Transmitting Data

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NAME	FUNCTION	PIN NO.
C2+	Positive terminal of the symmetrical charge-pump capacitor C2.	1
GND	Ground.	2
C2-	Negative terminal of the symmetrical charge-pump capacitor C2.	3
V-	Regulated -5.5V output generated by the charge pump.	4
T_1OUT	RS-232 driver output.	5
T_2OUT	RS-232 driver output.	6
T_3OUT	RS-232 driver output.	7
R_1IN	RS-232 receiver input.	8
R_2IN	RS-232 receiver input.	9
T_4OUT	RS-232 driver output.	10
R_3IN	RS-232 receiver input.	11
T_5OUT	RS-232 driver output.	12
T_5IN	TTL/CMOS driver input.	13
R_3OUT	TTL/CMOS receiver output.	14
T_4IN	TTL/CMOS driver input.	15
R_2OUT	TTL/CMOS receiver output.	16
R_1OUT	TTL/CMOS receiver output.	17
T_3IN	TTL/CMOS driver input.	18
T_2IN	TTL/CMOS driver input.	19
T_1IN	TTL/CMOS driver input.	20
C1-	Negative terminal of the symmetrical charge-pump capacitor C1.	21
V_{CC}	+3.0V to +5.5V supply voltage.	22
V+	Regulated +5.5V output generated by the charge pump.	23
C1+	Positive terminal of the voltage doubler charge-pump capacitor C1	24

Table 1. Device Pin Description

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PINOUT

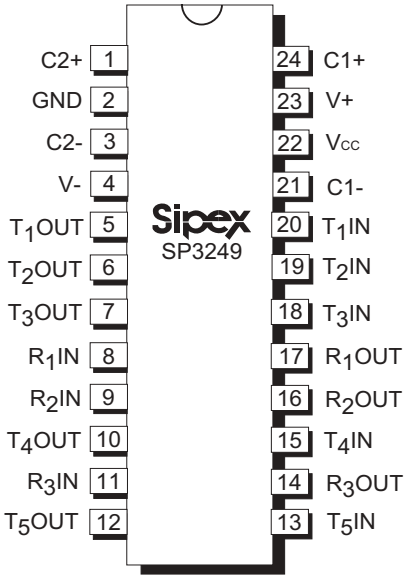

Figure 4. SP3249 Pinout Configuration

TYPICAL OPERATING CIRCUIT

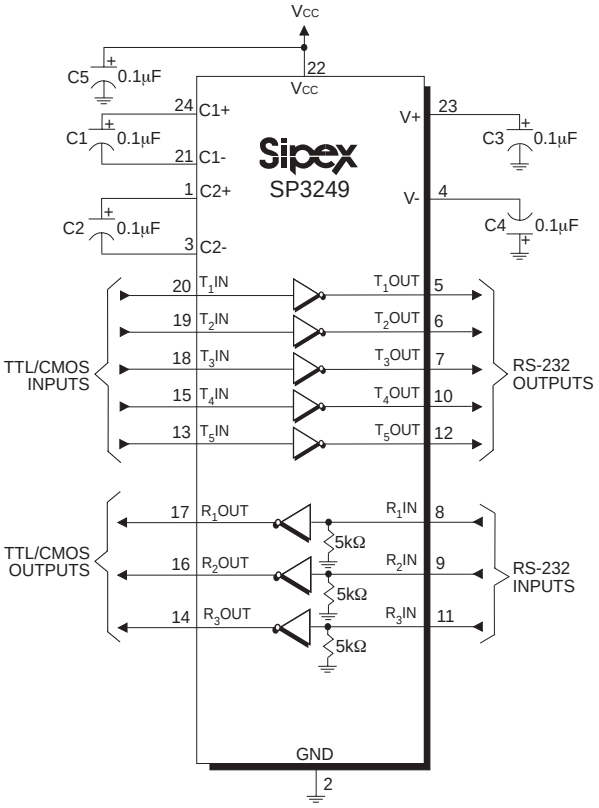

Figure 5. SP3249 Typical Connections

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DESCRIPTION

The SP3249 device meets the EIA/TIA-232 and ITU-T V.28/V.24 communication protocols and can be implemented in battery-powered, portable, or hand-held applications such as notebook or palmtop computers. The SP3249 device features Sipex's proprietary and patented (U.S. #5,306,954) on-board charge pump circuitry that generates ±5.5V RS-232 voltage levels from a single +3.0V to +5.5V power supply. The SP3249 device can operate at a data rate of 250kbps fully loaded.

The SP3249 is a 5-driver/3-receiver device, ideal for portable or hand-held applications.

The SP3249 device is an ideal choice for power sensitive designs.

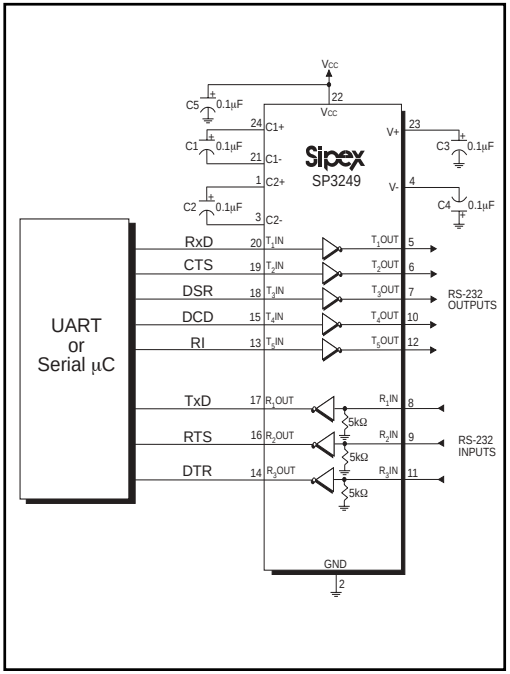

Figure 6. Typical Operating Circuit

THEORY OF OPERATION

The SP3249 device is made up of four basic circuit blocks: 1. Drivers, 2. Receivers, 3. the Sipex proprietary charge pump.

Drivers

The drivers are inverting level transmitters that convert TTL or CMOS logic levels to EIA/TIA-232 levels with an inverted sense relative to the input logic levels. Typically, the RS-232 output voltage swing is ±5.4V with no load and ±5V minimum fully loaded. The driver outputs are protected against infinite short-circuits to ground without degradation in reliability. These drivers comply with the EIA-TIA-232F and all previous RS-232 versions. All unused driver inputs must be connected to V_{CC} or GND.

The drivers can guarantee a data rate of 250kbps fully loaded with 3kΩ in parallel with 1000pF, ensuring compatibility with PC-to-PC communication software.

The slew rate of the driver output is internally limited to a maximum of 30V/µs in order to meet the EIA standards (EIA RS-232D 2.1.7, Paragraph 5). The transition of the loaded output from HIGH to LOW also meets the monotonicity requirements of the standard.

Figure 7 shows a loopback test circuit used to test the RS-232 Drivers. Figure 8 shows the test results of the loopback circuit with all five drivers active at 120kbps with typical RS-232 loads in parallel with 1000pF capacitors. Figure 9 shows the test results where one driver was active at 250kbps and all five drivers loaded with an RS-232 receiver in parallel with a 1000pF capacitor. A solid RS-232 data transmission rate of 120kbps provides compatibility with many designs in personal computer peripherals and LAN applications.

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Receivers

The receivers convert ±5.0V- 15V EIA/TIA-232 levels to TTL or CMOS logic output levels.

Since receiver input is usually from a transmission line where long cable lengths and system interference can degrade the signal, the inputs have a typical hysteresis margin of 500mV. This ensures that the receiver is virtually immune to noisy transmission lines. Should an input be left unconnected, an internal 5kΩ pulldown resistor to ground will commit the output of the receiver to a HIGH state.

Charge Pump

The charge pump is a Sipex–patented design (U.S. #5,306,954) and uses a unique approach compared to older less–efficient designs. The charge pump still requires four external capacitors, but uses a four–phase voltage shifting technique to attain symmetrical 5.5V power supplies. The internal power supply consists of a regulated dual charge pump that provides output voltages 5.5V regardless of the input voltage (V_{CC}) over the +3.0V to +5.5V range. This is important to maintain compliant RS-232 levels regardless of power supply fluctuations.

The charge pump operates in a discontinuous mode using an internal oscillator. If the output voltages are less than a magnitude of 5.5V, the charge pump is enabled. If the output voltages exceed a magnitude of 5.5V, the charge pump is disabled. This oscillator controls the four phases of the voltage shifting (Figure 13). A description of each phase follows.

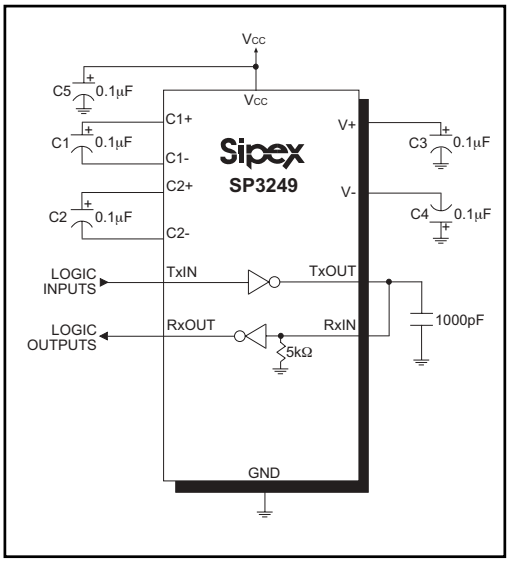

Figure 7. Loopback Test Circuit for RS-232 Driver Data Transmission Rates

Phase 1 (Figure 11)

— V_{SS} charge storage — During this phase of the clock cycle, the positive side of capacitors C_1 and C_2 are initially charged to V_{CC}. C_1^+ is then switched to GND and the charge in C_1^- is transferred to C_2^-. Since C_2^+ is connected to V_{CC}, the voltage potential across capacitor C_2 is now 2 times V_{CC}.

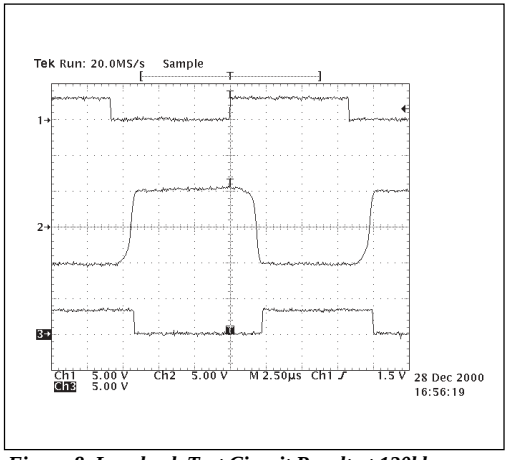

Figure 8. Loopback Test Circuit Result at 120kbps (All Drivers Fully Loaded)

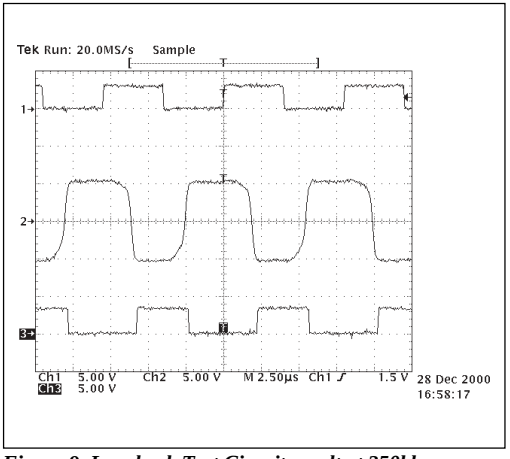

Figure 9. Loopback Test Circuit result at 250kbps (All Drivers Fully Loaded)

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Phase 2 (Figure 12)

— V_{SS} transfer — Phase two of the clock connects the negative terminal of C_2 to the V_{SS} storage capacitor and the positive terminal of C_2 to GND. This transfers a negative generated voltage to C_3. This generated voltage is regulated to a minimum voltage of -5.5V. Simultaneous with the transfer of the voltage to C_3, the positive side of capacitor C_1 is switched to V_{CC} and the negative side is connected to GND.

Phase 3 (Figure 14)

— V_{DD} charge storage — The third phase of the clock is identical to the first phase — the charge transferred in C_1 produces $-V_{CC}$ in the negative terminal of C_1, which is applied to the negative side of capacitor C_2. Since C_2^+ is at V_{CC}, the voltage potential across C_2 is 2 times V_{CC}.

Phase 4 (Figure 15)

— V_{DD} transfer — The fourth phase of the clock connects the negative terminal of C_2 to GND, and transfers this positive generated voltage across C_2 to C_4, the V_{DD} storage capacitor. This voltage is regulated to +5.5V. At this voltage, the internal oscillator is disabled. Simultaneous with the transfer of the voltage to C_4, the positive side of capacitor C_1 is switched to V_{CC} and the negative side is connected to GND, allowing the charge pump cycle to begin again. The charge pump cycle will continue as long as the operational conditions for the internal oscillator are present.

Since both V^+ and V^- are separately generated from V_{CC}, in a no–load condition V^+ and V^- will be symmetrical. Older charge pump approaches that generate V^- from V^+ will show a decrease in the magnitude of V^- compared to V^+ due to the inherent inefficiencies in the design.

The clock rate for the charge pump typically operates at 500kHz. The external capacitors can be as low as 0.1µF with a 16V breakdown voltage rating.

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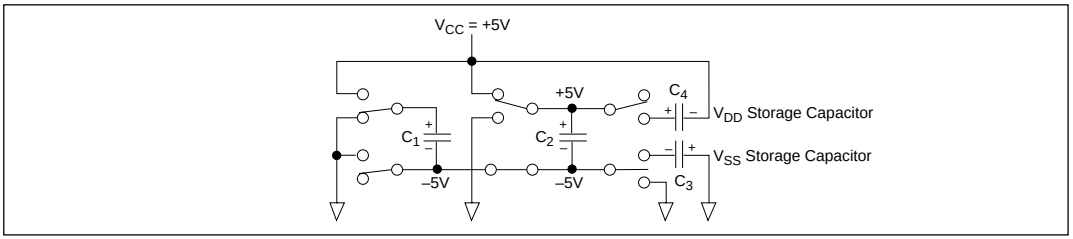

Figure 10. Charge Pump — Phase 1

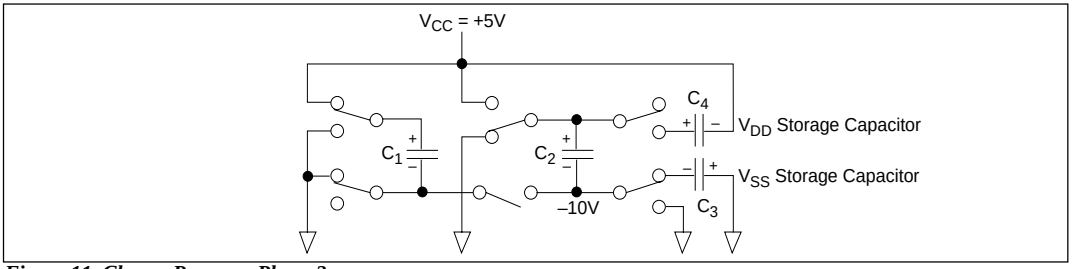

Figure 11. Charge Pump — Phase 2

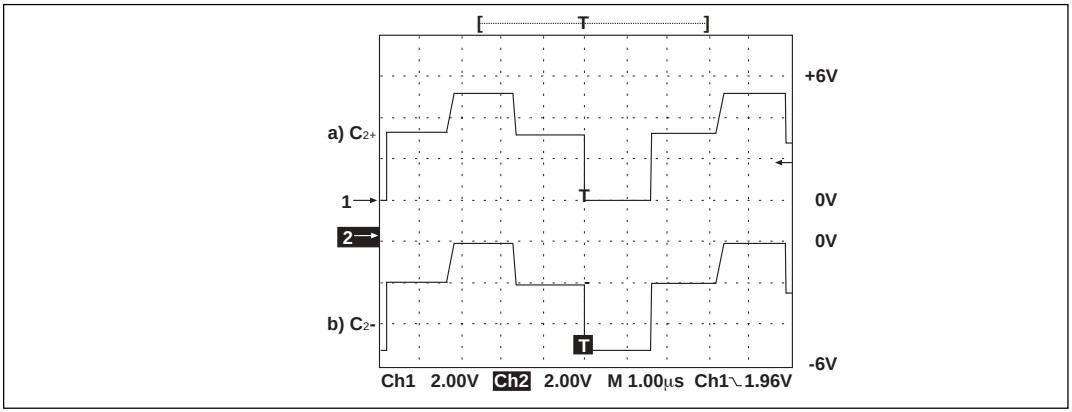

Figure 12. Charge Pump Waveforms

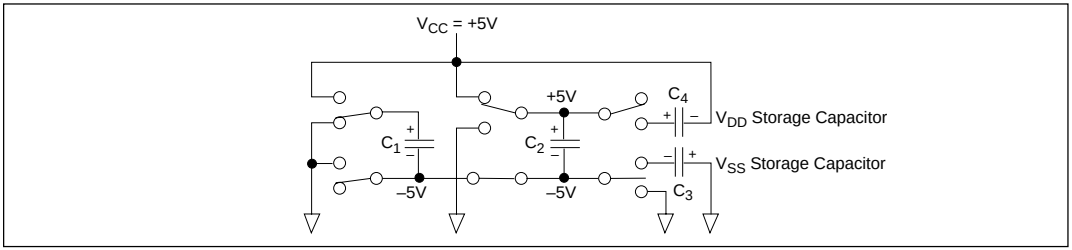

Figure 13. Charge Pump — Phase 3

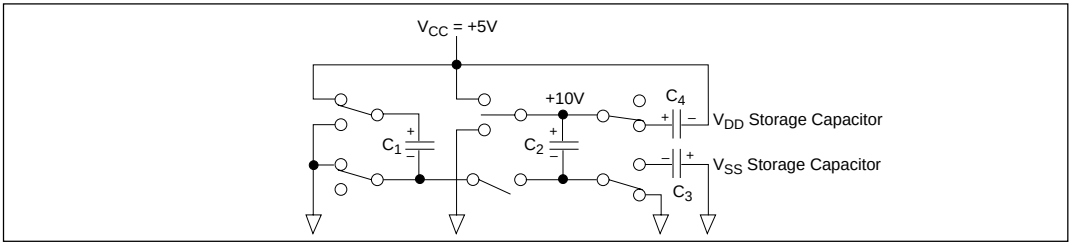

Figure 14. Charge Pump — Phase 4

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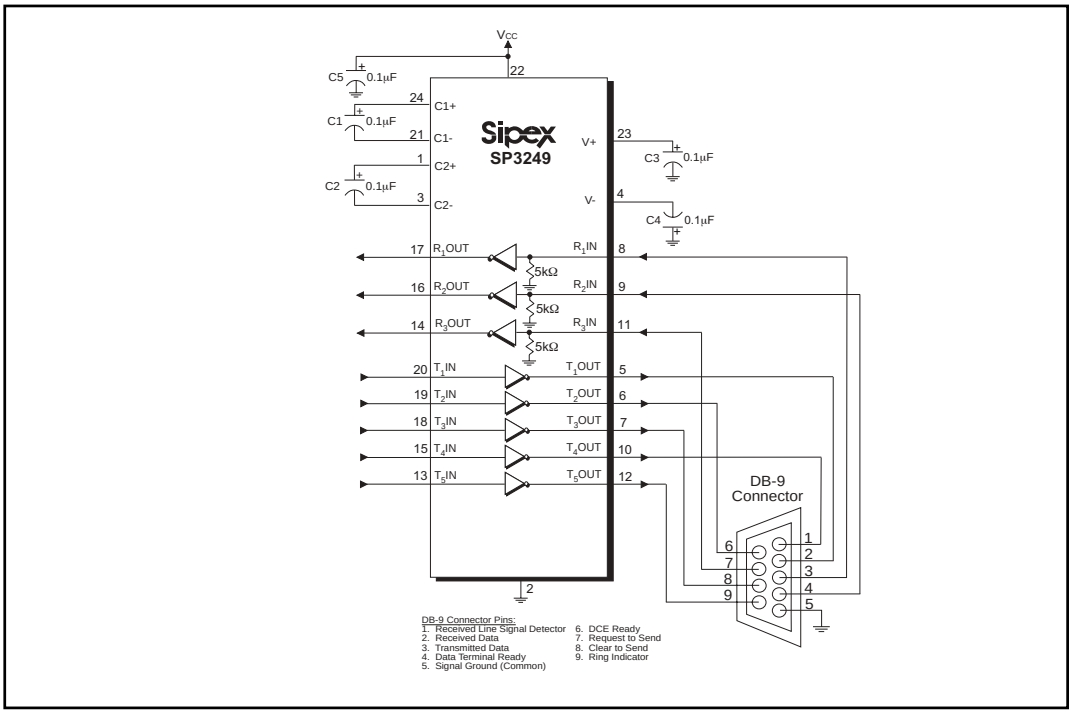

Figure 15. Circuit for the connectivity of the SP3249 with a DB-9 connector

ESD TOLERANCE

The SP3249 device incorporates ruggedized ESD cells on all driver output and receiver input pins. The ESD structure is improved over our previous family for more rugged applications and environments sensitive to electro-static discharges and associated transients.

The Human Body Model has been the generally accepted ESD testing method for semiconductors. This method is also specified in MIL-STD-883, Method 3015.7 for ESD testing. The premise of this ESD test is to simulate the human body's potential to store electro-static energy and discharge it to an integrated circuit. The simulation is performed by using a test model as shown in Figure 16. This method will test the IC's capability to withstand an ESD transient during normal handling such as in manufacturing areas where the ICs tend to be handled frequently.

For the Human Body Model, the current limiting resistor (R_S) and the source capacitor (C_S) are 1.5kΩ and 100pF, respectively.

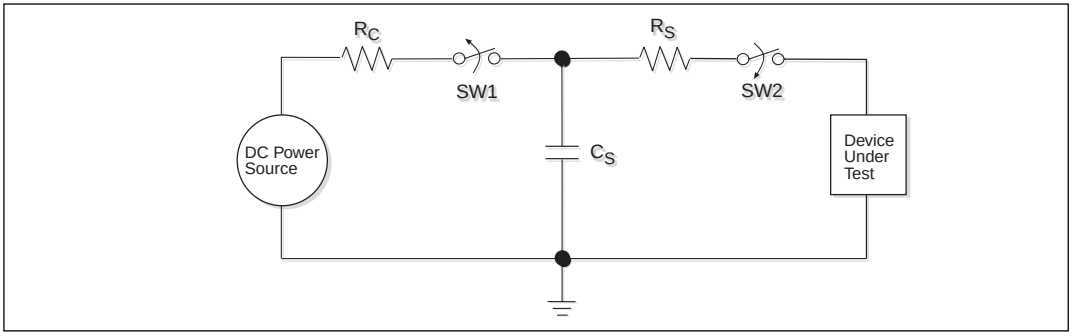

Figure 16. ESD Test Circuit for Human Body Model

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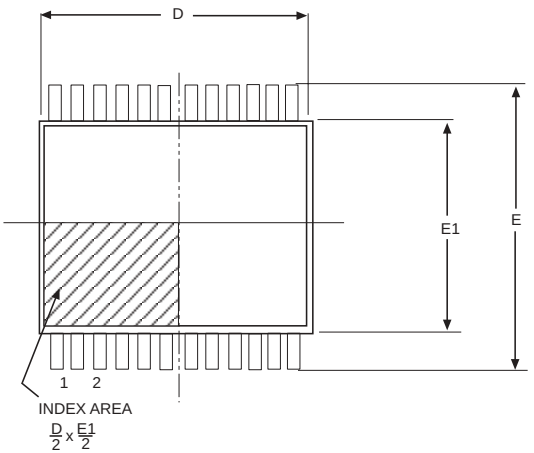
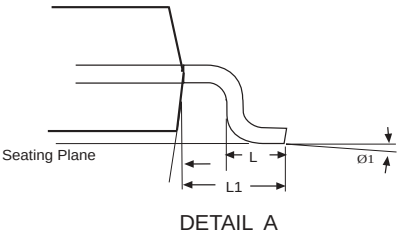
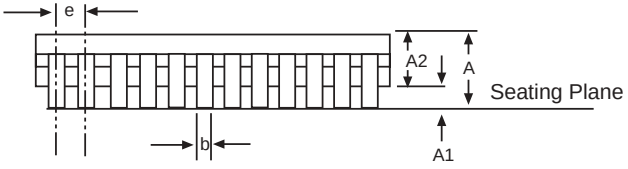
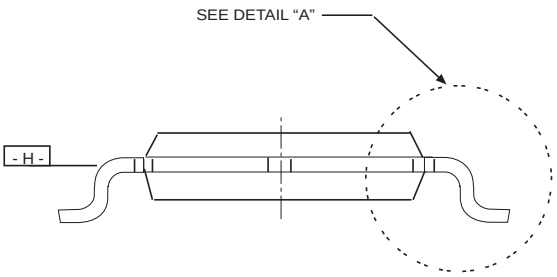
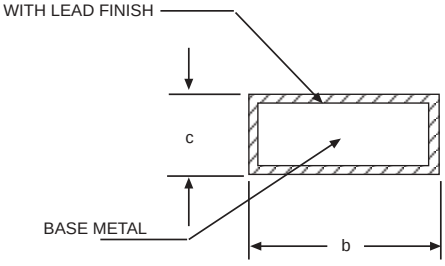






24 PIN SSOP JEDEC MO-150 (AG) Variation	Dimensions in (mm)		
	MIN	NOM	MAX
A	-	-	2.0
A1	0.05	-	-
A2	1.65	1.75	1.85
b	0.22	-	0.38
c	0.09	-	0.25
D	7.90	8.20	8.50
e	0.65 BSC		
E	7.40	7.80	8.20
E1	5.00	5.30	5.60
L	0.55	0.75	0.95
L1	1.25 REF		
Ø	0º	4º	8º





24 PIN SSOP

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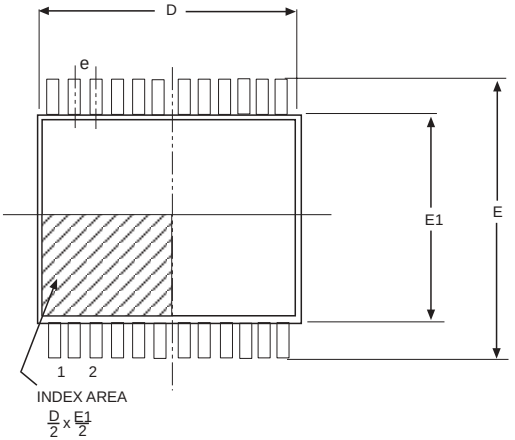
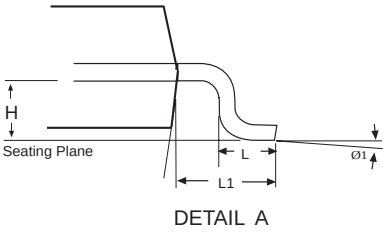
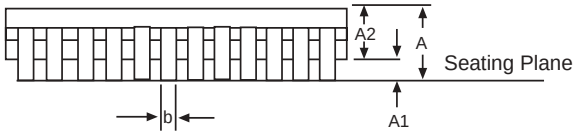
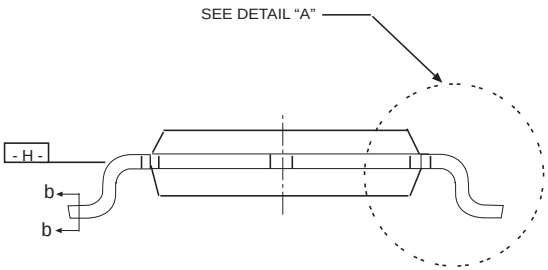
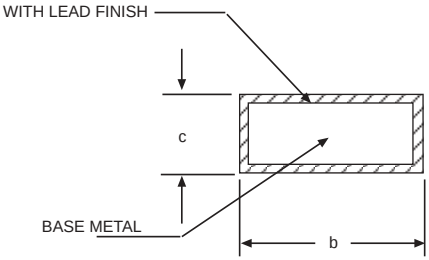






24 PIN TSSOP JEDEC MO-153 (AD) Variation	Dimensions in (mm)		
	MIN	NOM	MAX
A	-	-	1.20
A1	0.05	-	0.15
A2	0.80	1.00	1.05
b	0.19	-	0.30
c	0.09	-	0.20
D	7.70	7.80	7.90
e	0.65 BSC		
E	6.40 BSC		
E1	4.30	4.40	4.50
L	0.80	1.00	1.05
L1	1.00 REF		
ø1	0º	4º	8º





24 PIN TSSOP

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ORDERING INFORMATION

Model	Temperature Range	Package Types
SP3249CA	0°C to +70°C	24-pin SSOP
SP3249CY	0°C to +70°C	24-pin TSSOP
SP3249EA	-40°C to +85°C	24-pin SSOP
SP3249EY	-40°C to +85°C	24-pin TSSOP

Please consult the factory for pricing and availability on a Tape-On-Reel option.

Sipex Corporation

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